PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YA-LIEN LEE	06/03/2014
HUNG-WEN SU	06/04/2014
YU-HUNG LIN	05/28/2014
KUEI-PIN LEE	03/06/2014
YU-MIN CHANG	05/29/2014

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14286859

CORRESPONDENCE DATA

Fax Number: (214)200-0853

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 214-651-5000
Email: ipdocketing@haynesboone.com
Correspondent Name: HAYNES AND BOONE, LLP IP SECTION
Address Line 1: 2323 VICTORY AVENUE
Address Line 2: SUITE 700
Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	2012-0683-CIP/24061.2908
NAME OF SUBMITTER:	LYDIA EPPS-HILLIARD
SIGNATURE:	/LYDIA EPPS-HILLIARD/
DATE SIGNED:	08/04/2014

Total Attachments: 3

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Docket No.: 2012-0683-CIP/24061.2908
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Ya-Lien Lee of No. 8, Alley. 19, Lane 80, Songcui Road
Baoshan Township, Hsinchu County 308
Taiwan, R.O.C.

(2) Hung-Wen Su of No. 190-2, Guangming 9th Road, Jhubei City
Hsinchu County 302, Taiwan, R.O.C.

(3) Yu-Hung Lin of No. 279, Section 2, Qinghai Road, Xitun District
Taichung City 407, Taiwan, R.O.C.

(4) Kuei-Pin Lee of 11F.-1, No. 156, Minyou Street, Linkou District
New Taipei City 244, Taiwan, R.O.C.

(5) Yu-Min Chang of 4F.-3, No. 67, Gaocui Road, East District
Hsinchu City 300, Taiwan, R.O.C.

have invented certain improvements in

DEVICE AND METHOD FOR REDUCING CONTACT RESISTANCE OF A METAL

for which we have filed an application for Letters Patent of the United States of America on May 23, 2014, as U.S. Serial No. 14/286,859; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ya-Lien Lee

Residence Address: No. 8, Alley. 19, Lane 80, Songcui Road, Baoshan Township
Hsinchu County 308, Taiwan, R.O.C.

Dated: 2014/06/03

Ya-Lien Lee
Inventor Signature

Inventor Name: Hung-Wen Su

Residence Address: No. 190-2, Guangming 9th Road, Jhubei City
Hsinchu County 302, Taiwan, R.O.C.

Dated: 2014. 6. 4

Hung-Wen Su
Inventor Signature

Inventor Name: Yu-Hung Lin

Residence Address: No. 279, Section 2, Qinghai Road, Xitun District
Taichung City 407, Taiwan, R.O.C.

Dated: ~~Yu-Hung Lin~~
2014.05.28

Yu-Hung Lin
Inventor Signature

Inventor Name: Kuei-Pin Lee

Residence Address: 11F.-1, No. 156, Minyou Street, Linkou District
New Taipei City 244, Taiwan, R.O.C.

Dated: 2014.06.03

Kuei-Pin Lee
Inventor Signature

Inventor Name: Yu-Min Chang

Residence Address: 4F.-3, No. 67, Gaocui Road, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2014. 5. 29

Yu-Min Chang
Inventor Signature
